

GL12 / GL22 (铝基覆铜板/AL_CCL $1.0 < \lambda \leq 1.5 \text{ W/m}\cdot\text{K}$)

特点

- 良好的导热性能
- 良好的绝缘性
- 优异的尺寸稳定性
- 高性价比
- GL12为表面阳极氧化铝基板
GL22为非表面阳极氧化铝基板

应用领域

- LED照明
- LED电视
- 功率放大器、交换机、汽车电子设备
- 输入输出放大器、DC/AC转换器
- 整流器、高功率晶体管等

FEATURES

- Excellent Thermal Conductance
- Good Insulation
- Excellent Dimensional Stability
- Cost-effective
- GL12 Surface Anodic Oxidation Treatment CCL
GL22 Free Surface Anodic Oxidation Treatment CCL

APPLICATIONS

- LED Lighting
- LED TV
- Power Amplifier, Switch, Auto-electrics
- I/O Amplifier, DC/AC Converter
- Rectifier, High Power Transistors

GL12 / GL22 (铝基覆铜板/AL_CCL $1.5 < \lambda \leq 2.0 \text{ W/m}\cdot\text{K}$)

特点

- 优异的导热性能
- 良好的绝缘性
- 优异的尺寸稳定性
- 优良的加工性
- 高性价比
- GL12为表面阳极氧化铝基板
GL22为非表面阳极氧化铝基板

应用领域

- 大功率LED照明
- LED电视
- 功率放大器、交换机、汽车电子设备
- 输入输出放大器、DC/AC转换器
- 整流器、高功率晶体管等

FEATURES

- Excellent Thermal Conductance
- Good Insulation
- Excellent Dimensional Stability
- Excellent Processability
- Cost-effective
- GL12 Surface Anodic Oxidation Treatment CCL
GL22 Free Surface Anodic Oxidation Treatment CCL

APPLICATIONS

- High Power LED Lighting
- LED TV
- Power Amplifier, Switch, Auto-electrics
- I/O Amplifier, DC/AC Converter
- Rectifier, High Power Transistors

GENERAL PROPERTIES

Item	Test Condition	Unit	Specification	Actual Value
Thermal Conductivity	CPCA-4105-2010	W/m·K	$1.0 < \lambda \leq 1.5$	1.1
Heat Resistance	CPCA-4105-2010	K·m ² /W	$\leq 1.0 \times 10^{-4}$	0.99×10^{-4}
Thermal Stress	288°C Solder Float	S	288°C ≥ 120	180
Peel Strength	288°C/10s Float	LBS/IN	≥ 6	7
Dielectric Breakdown	AC	KV	≥ 2	4
CTI	IEC60112	V	/	400
TG	DSC	°C	AABUS	120
Surface Resistivity	E24/125	Ω	$\geq 1.0 \times 10^4$	10^6
Volume Resistivity	E24/125	Ωcm	$\geq 1.0 \times 10^6$	10^8
Moisture Absorption	D24/23	%	≤ 1.5	0.44
Flammability	UL94	/	V-0	ACC

注：1. 上表中击穿电压，铝基覆铜板按CPCA 4105-2010 C.8 AC条件下进行测试可满足要求。
2. 铝基PCB板击穿电压因受边缘线距的影响，飞弧、爬电现象会使测试电压偏低，因此建议在油浴状态下进行检测评估基板耐电压性能。
Note: 1. The Dielectric Breakdown value would meet the requirements according to the CPCA 4105-2010 C.8 AC standard.
2. Because of the impact of the flashover and creepage caused by lower creepage distance, the Dielectric Breakdown value of Al Base PCB will be down. The test should be performed under oil bath conditions.

GENERAL PROPERTIES

Item	Test Condition	Unit	Specification	Actual Value
Thermal Conductivity	CPCA-4105-2010	W/m·K	$1.5 < \lambda \leq 2.0$	1.8
Heat Resistance	CPCA-4105-2010	K·m ² /W	$\leq 0.5 \times 10^{-4}$	0.55×10^{-4}
Thermal Stress	288°C solder Float	S	288°C ≥ 120	180
Peel Strength	288°C/10s Float	LBS/IN	≥ 6	7
Dielectric Breakdown	AC	KV	≥ 2	4
CTI	IEC60112	V	/	400
TG	DSC	°C	AABUS	120
Surface Resistivity	E24/125	Ω	$\geq 1.0 \times 10^4$	10^6
Volume Resistivity	E24/125	Ωcm	$\geq 1.0 \times 10^6$	10^8
Moisture Absorption	D24/23	%	≤ 1.5	0.42
Flammability	UL94	/	V-0	ACC

注：1. 上表中击穿电压，按CPCA 4105-2010 C.8 AC条件下进行测试可满足要求。
2. 铝基PCB板击穿电压因受边缘线距的影响，飞弧、爬电现象会使测试电压偏低，因此建议在油浴状态下进行检测评估基板耐电压性能。
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规格 Specification:
产品厚度 Thickness: 0.8mm; 1.0mm; 1.2mm; 1.5 mm; 1.6mm; 2.0mm
铜箔规格 Copper foil: 18 μm; 1oz; 1.5oz; 2oz; 3oz; 28 μm
供应尺寸 Size: 1000x1200mm; 1050x1250mm; 特殊尺寸单独定制 Specific size can be afford independently.

规格 Specification:
产品厚度 Thickness: 0.8mm; 1.0mm; 1.2mm; 1.5 mm; 1.6mm; 2.0mm
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